IN THE CLAIMS:

1. (Currently Amended) A semiconductor device comprising:

a substrate; and

a semiconductor element and at least one security coating provided on a first side of the substrate so as to block visual access to secure data, the at least one security coating including at least two powdery fillers incorporated in a matrix **comprising about 10 to 90 percent by weight of the security coating**,

wherein a first powdery filler scatters at least visible light, and a difference between a refractive index of the first powdery filler and that of the matrix is at least 0.3, and the coating comprises a second powdery filler which is a substantial absorber of radiation and is present in ~~sufficient quantity~~ **an amount of about 25% of the weight of the matrix,** so as to transform radiation into heat and ~~absorbs~~ **absorb** at least 99% of infrared radiation in contact therewith of wavelengths in the range of about 800 to 1400 nm and is free of heavy metals.

2. (Currently Amended) A semiconductor device as claimed in Claim 1, wherein the **first filler comprises TiO_2 and the** second filler comprises TiN.

3. (Currently Amended) A semiconductor device as claimed in Claim ~~1~~ **2**, wherein ~~**the first filler comprises TiO2**~~ **a weight ratio of the TiO_2 and TiN in the security coating ranges from about 0.25 to 4**.

4. (Currently Amended) A semiconductor device as claimed in Claim 1, wherein the matrix of the security coating comprises **a mono (metal)phosphate, wherein the metal is selected from the group consisting of aluminum, zinc and a component prepared form a precursor resin.**

5. (Currently Amended) A semiconductor device as claimed in Claim 1, where the security coating has a thickness of less than 3 *u*m **and the matrix of the security coating comprises monoaluminumphosphate**.

6. (Previously presented) A semiconductor device as claimed in Claim 1, further comprising a light-sensitive element and an element containing data, wherein the light-sensitive element and the element containing data are covered by the security coating and wherein the light-sensitive element, after the coating is damaged, reacts to exposure to visible light by inducing a permanent change of state of the element containing data.

7. (Previously presented) A semiconductor device as claimed in Claim 1, further comprising a light-sensitive element and an electrically programmable element containing data, wherein the light-sensitive element and the element containing data are covered by the security coating and the light sensitive element, after the coating is damaged, reacts to exposure to visible light by inducing erasure of the data and by bringing the electrically programmable element into a non-programmable state.

8. (Currently Amended) A smartcard provided with a semiconductor device comprising a memory and a security coating which comprises a powdery first filler that scatters at least visible light, said powdery first filler being incorporated in a matrix, wherein

- the coating comprises a second filler which is an absorber of radiation of a wavelength in the range of from 800 to 1400 nm, and

- the difference between the refractive index of the first filler and that of the matrix is at least 0.3; and wherein

the second filler is present in ~~sufficient~~ **a** quantity **of about an equal amount by weight as the first filler** so as to transform radiation into heat and absorbs at least 99% of infrared radiation in contact therewith.